

ON Semiconductor®

FDN5618P

60V P-Channel Logic Level PowerTrench® MOSFET

General Description

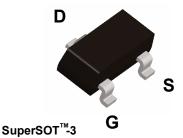
This 60V P-Channel MOSFET uses ON Semiconductor's high voltage PowerTrench process. It has been optimized for power management applications.

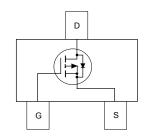
Applications

- DC-DC converters
- Load switch
- Power management

Features

- -1.25 A, -60 V. $R_{DS(ON)}$ = 0.170 Ω @ V_{GS} = -10 V $R_{DS(ON)}$ = 0.230 Ω @ V_{GS} = -4.5 V
- · Fast switching speed
- High performance trench technology for extremely low $R_{\ensuremath{\mathsf{DS}}(\ensuremath{\mathsf{ON}})}$





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units	
V_{DSS}	Drain-Source Voltage		-60	V	
V_{GSS}	Gate-Source Voltage		±20	V	
I _D	Drain Current - Continuous	(Note 1a)	-1.25	Α	
	- Pulsed		-10		
P _D	Maximum Power Dissipation	(Note 1a)	0.5	W	
		(Note 1b)	0.46		
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C	

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	250	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	75	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity	
618	FDN5618P	7"	8mm	3000 units	

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	racteristics					I
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-60			V
ΔBV _{DSS} ΔT, _J	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A,Referenced to 25°C		- 58		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -48 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μΑ
GSSF	Gate–Body Leakage, Forward	$V_{GS} = 20V$, $V_{DS} = 0 V$			100	nA
I_{GSSR}	Gate-Body Leakage, Reverse	V _{GS} = -20 V V _{DS} = 0 V			-100	nA
On Char	racteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-1	-1.6	-3	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	I_D = -250 μ A,Referenced to 25°C		4		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	$\begin{array}{cccccccccccccccccccccccccccccccccccc$		0.148 0.185 0.245	0.170 0.230 0.315	Ω
I _{D(on)}	On–State Drain Current	$V_{GS} = -10 \text{ V}, \qquad V_{DS} = -5 \text{ V}$	- 5			Α
g FS	Forward Transconductance	$V_{DS} = -5 \text{ V}, \qquad I_{D} = -1.25 \text{ A}$		4.3		S
Dvnamio	Characteristics			•	•	•
C _{iss}	Input Capacitance	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V},$		430		pF
Coss	Output Capacitance	f = 1.0 MHz		52		pF
C _{rss}	Reverse Transfer Capacitance	<u> </u>		19		pF
Switchir	ng Characteristics (Note 2)					I
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -30 \text{ V}, \qquad I_{D} = -1 \text{ A},$		6.5	13	ns
t_r	Turn-On Rise Time	$V_{GS} = -10 \text{ V}, \qquad R_{GEN} = 6 \Omega$		8	16	ns
$t_{d(off)}$	Turn-Off Delay Time	7		16.5	30	ns
t _f	Turn-Off Fall Time	7		4	8	ns
Q_g	Total Gate Charge	$V_{DS} = -30 \text{ V}, \qquad I_{D} = -1.25 \text{ A},$		8.6	13.8	nC
Q _{gs}	Gate-Source Charge	V _{GS} = -10 V		1.5		nC
Q_{gd}	Gate-Drain Charge			1.3		nC
Drain-S	ource Diode Characteristics	and Maximum Ratings				
I _s	Maximum Continuous Drain–Source				-0.42	Α
V _{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = -0.42 \text{(Note 2)}$		-0.7	-1.2	V

Notes:

^{1.} R_{e,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $\rm R_{\theta JC}$ is guaranteed by design while $\rm R_{\theta CA}$ is determined by the user's board design.



a) 250°C/W when mounted on a 0.02 in² pad of 2 oz. copper.

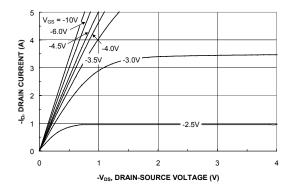


b) 270°C/W when mounted on a minimum pad.

Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width $\leq 300~\mu\text{s},~\text{Duty Cycle} \leq 2.0$

Typical Characteristics



2.2

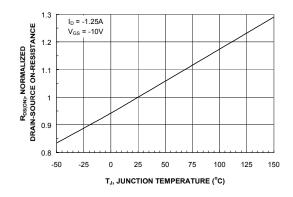
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Figure 1. On-Region Characteristics.

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.



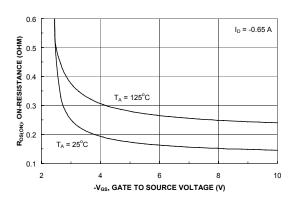
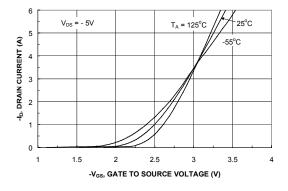


Figure 3. On-Resistance Variation withTemperature.

Figure 4. On-Resistance Variation with Gate-to-Source Voltage.



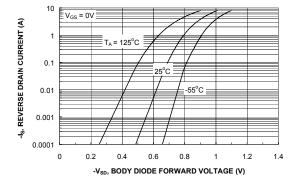
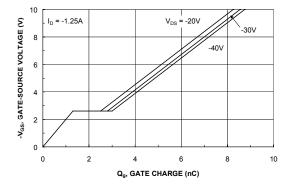


Figure 5. Transfer Characteristics.

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



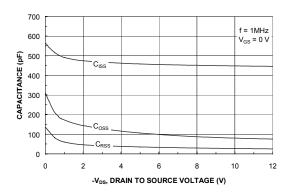


Figure 7. Gate Charge Characteristics.

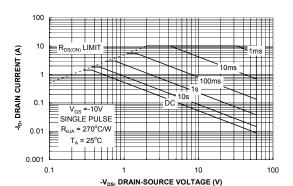


Figure 8. Capacitance Characteristics.

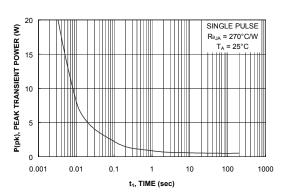


Figure 9. Maximum Safe Operating Area.



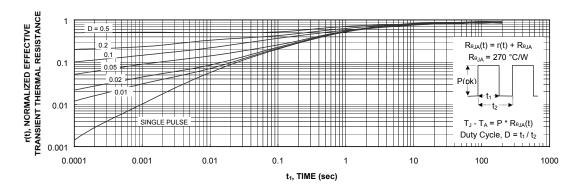


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.

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